



Welcome to [E-XFL.COM](https://www.e-xfl.com)

### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	225400
Number of Logic Elements/Cells	597000
Total RAM Bits	53248000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-FCBGA (42.5x42.5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgxeb6r3f43i3n">https://www.e-xfl.com/product-detail/intel/5sgxeb6r3f43i3n</a>

### I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

**Table 9. I/O Pin Leakage Current for Stratix V Devices <sup>(1)</sup>**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$

**Note to Table 9:**

(1) If  $V_O = V_{CCIO}$  to  $V_{CCIO\text{MAX}}$ , 100  $\mu\text{A}$  of leakage current per I/O is expected.

### Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

**Table 10. Bus Hold Parameters for Stratix V Devices**

Parameter	Symbol	Conditions	V <sub>CCIO</sub>										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
High sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (minimum)	−22.5	—	−25.0	—	−30.0	—	−50.0	—	−70.0	—	μA
Low overdrive current	I <sub>ODL</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	120	—	160	—	200	—	300	—	500	μA
High overdrive current	I <sub>ODH</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−120	—	−160	—	−200	—	−300	—	−500	μA
Bus-hold trip point	V <sub>TRIP</sub>	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

### On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices <sup>(1)</sup> (Part 1 of 2)**

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
25- $\Omega$ $R_S$	Internal series termination with calibration (25- $\Omega$ setting)	$V_{\text{CCIO}} = 3.0, 2.5, 1.8, 1.5, 1.2 \text{ V}$	$\pm 15$	$\pm 15$	$\pm 15$	$\pm 15$	%

## Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

**Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices <sup>(1), (2)</sup>**

Symbol	Description	V <sub>CCIO</sub> Conditions (V) <sup>(3)</sup>	Value <sup>(4)</sup>	Unit
R <sub>PU</sub>	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
		1.8 ±5%	25	kΩ
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

### Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V<sub>CCIO</sub>.
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

## I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V<sub>IH</sub> and V<sub>IL</sub>), output voltage (V<sub>OH</sub> and V<sub>OL</sub>), and current drive characteristics (I<sub>OH</sub> and I<sub>OL</sub>) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V<sub>OL</sub> and V<sub>OH</sub> values are valid at the corresponding I<sub>OH</sub> and I<sub>OL</sub>, respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to “Glossary” on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012\_486.

**Table 17. Single-Ended I/O Standards for Stratix V Devices**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>IL</sub> (V)		V <sub>IH</sub> (V)		V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub> (mA)	I <sub>OH</sub> (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LVTTTL	2.85	3	3.15	−0.3	0.8	1.7	3.6	0.4	2.4	2	−2
LVC MOS	2.85	3	3.15	−0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> − 0.2	0.1	−0.1
2.5 V	2.375	2.5	2.625	−0.3	0.7	1.7	3.6	0.4	2	1	−1
1.8 V	1.71	1.8	1.89	−0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.45	V <sub>CCIO</sub> − 0.45	2	−2
1.5 V	1.425	1.5	1.575	−0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	−2
1.2 V	1.14	1.2	1.26	−0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	−2

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 3 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reconfiguration clock ( <code>mgmt_clk_clk</code> ) frequency	—	100	—	125	100	—	125	100	—	125	MHz
<b>Receiver</b>											
Supported I/O Standards	—	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Data rate (Standard PCS) <sup>(9), (23)</sup>	—	600	—	12200	600	—	12200	600	—	8500/ 10312.5 <sup>(24)</sup>	Mbps
Data rate (10G PCS) <sup>(9), (23)</sup>	—	600	—	14100	600	—	12500	600	—	8500/ 10312.5 <sup>(24)</sup>	Mbps
Absolute $V_{MAX}$ for a receiver pin <sup>(5)</sup>	—	—	—	1.2	—	—	1.2	—	—	1.2	V
Absolute $V_{MIN}$ for a receiver pin	—	−0.4	—	—	−0.4	—	—	−0.4	—	—	V
Maximum peak- to-peak differential input voltage $V_{ID}$ (diff p- p) before device configuration <sup>(22)</sup>	—	—	—	1.6	—	—	1.6	—	—	1.6	V
Maximum peak- to-peak differential input voltage $V_{ID}$ (diff p- p) after device configuration <sup>(18)</sup> , <sup>(22)</sup>	$V_{CCR\_GXB} =$ 1.0 V/1.05 V ( $V_{ICM} =$ 0.70 V)	—	—	2.0	—	—	2.0	—	—	2.0	V
	$V_{CCR\_GXB} =$ 0.90 V ( $V_{ICM} = 0.6$ V)	—	—	2.4	—	—	2.4	—	—	2.4	V
	$V_{CCR\_GXB} =$ 0.85 V ( $V_{ICM} = 0.6$ V)	—	—	2.4	—	—	2.4	—	—	2.4	V
Minimum differential eye opening at receiver serial input pins <sup>(6)</sup> , <sup>(22)</sup> , <sup>(27)</sup>	—	85	—	—	85	—	—	85	—	—	mV

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 5 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	2	—	—	2	—	—	2	—	dB
	DC Gain Setting = 2	—	4	—	—	4	—	—	4	—	dB
	DC Gain Setting = 3	—	6	—	—	6	—	—	6	—	dB
	DC Gain Setting = 4	—	8	—	—	8	—	—	8	—	dB
<b>Transmitter</b>											
Supported I/O Standards	—	1.4-V and 1.5-V PCML									
Data rate (Standard PCS)	—	600	—	12200	600	—	12200	600	—	8500/ 10312.5 <sup>(24)</sup>	Mbps
Data rate (10G PCS)	—	600	—	14100	600	—	12500	600	—	8500/ 10312.5 <sup>(24)</sup>	Mbps
Differential on- chip termination resistors	85- $\Omega$ setting	—	85 $\pm$ 20%	—	—	85 $\pm$ 20%	—	—	85 $\pm$ 20%	—	$\Omega$
	100- $\Omega$ setting	—	100 $\pm$ 20%	—	—	100 $\pm$ 20%	—	—	100 $\pm$ 20%	—	$\Omega$
	120- $\Omega$ setting	—	120 $\pm$ 20%	—	—	120 $\pm$ 20%	—	—	120 $\pm$ 20%	—	$\Omega$
	150- $\Omega$ setting	—	150 $\pm$ 20%	—	—	150 $\pm$ 20%	—	—	150 $\pm$ 20%	—	$\Omega$
V <sub>OCM</sub> (AC coupled)	0.65-V setting	—	650	—	—	650	—	—	650	—	mV
V <sub>OCM</sub> (DC coupled)	—	—	650	—	—	650	—	—	650	—	mV
Rise time <sup>(7)</sup>	20% to 80%	30	—	160	30	—	160	30	—	160	ps
Fall time <sup>(7)</sup>	80% to 20%	30	—	160	30	—	160	30	—	160	ps
Intra-differential pair skew	Tx V <sub>CM</sub> = 0.5 V and slew rate of 15 ps	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	—	—	120	—	—	120	—	—	120	ps

Figure 4 shows the differential transmitter output waveform.

**Figure 4. Differential Transmitter/Receiver Output/Input Waveform**

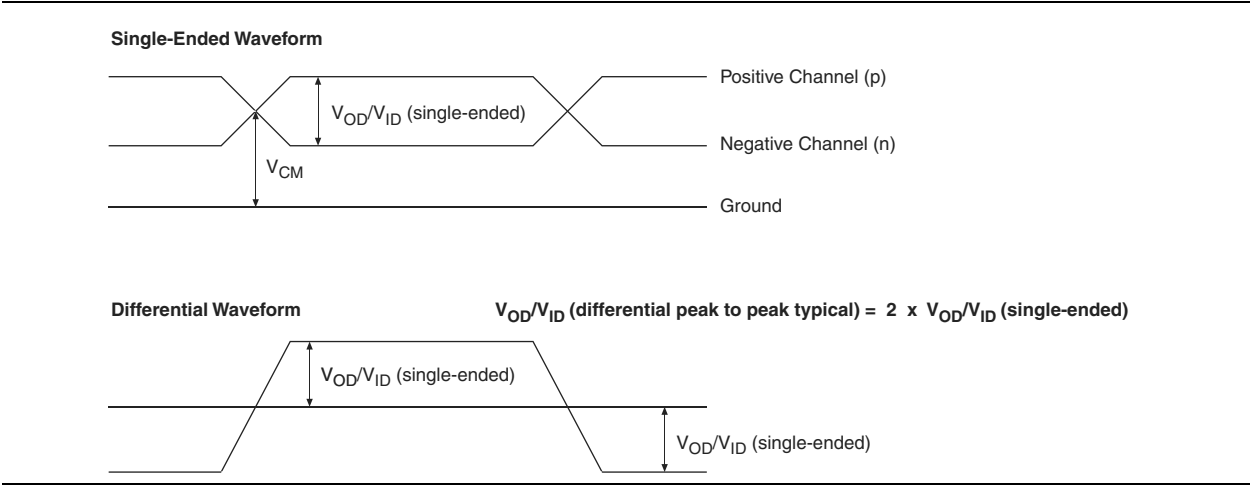


Figure 5 shows the Stratix V AC gain curves for GT channels.

**Figure 5. AC Gain Curves for GT Channels**

## PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (–40° to 100°C).

**Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$f_{IN}$	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	—	800 <sup>(1)</sup>	MHz
	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	—	800 <sup>(1)</sup>	MHz
	Input clock frequency (C4, I4 speed grades)	5	—	650 <sup>(1)</sup>	MHz
$f_{INPFD}$	Input frequency to the PFD	5	—	325	MHz
$f_{FINPFD}$	Fractional Input clock frequency to the PFD	50	—	160	MHz
$f_{VCO}$ <sup>(9)</sup>	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	—	1600	MHz
	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	—	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%
$f_{OUT}$	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	—	717 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	—	—	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	—	—	580 <sup>(2)</sup>	MHz
$f_{OUT\_EXT}$	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	—	—	800 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C3, I3, I3L speed grades)	—	—	667 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	—	—	553 <sup>(2)</sup>	MHz
$t_{OUTDUTY}$	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
$t_{FCOMP}$	External feedback clock compensation time	—	—	10	ns
$f_{DYCONFIGCLK}$	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	—	—	100	MHz
$t_{LOCK}$	Time required to lock from the end-of-device configuration or deassertion of <code>areset</code>	—	—	1	ms
$t_{DLOCK}$	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
$f_{CLBW}$	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth <sup>(7)</sup>	—	4	—	MHz
$t_{PLL\_PSERR}$	Accuracy of PLL phase shift	—	—	±50	ps
$t_{ARESET}$	Minimum pulse width on the <code>areset</code> signal	10	—	—	ns

**Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{\text{INCCJ}}$ <sup>(3), (4)</sup>	Input clock cycle-to-cycle jitter ( $f_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter ( $f_{\text{REF}} < 100$ MHz)	−750	—	+750	ps (p-p)
$t_{\text{OUTPJ\_DC}}$ <sup>(5)</sup>	Period Jitter for dedicated clock output ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	175 <sup>(1)</sup>	ps (p-p)
	Period Jitter for dedicated clock output ( $f_{\text{OUT}} < 100$ MHz)	—	—	17.5 <sup>(1)</sup>	mUI (p-p)
$t_{\text{FOUTPJ\_DC}}$ <sup>(5)</sup>	Period Jitter for dedicated clock output in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
	Period Jitter for dedicated clock output in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_DC}}$ <sup>(5)</sup>	Cycle-to-Cycle Jitter for a dedicated clock output ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle-to-Cycle Jitter for a dedicated clock output ( $f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{FOUTCCJ\_DC}}$ <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)+	—	—	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
$t_{\text{OUTPJ\_IO}}$ <sup>(5), (8)</sup>	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O ( $f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{FOUTPJ\_IO}}$ <sup>(5), (8), (11)</sup>	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600 <sup>(10)</sup>	ps (p-p)
	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	60 <sup>(10)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_IO}}$ <sup>(5), (8)</sup>	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	60 <sup>(10)</sup>	mUI (p-p)
$t_{\text{FOUTCCJ\_IO}}$ <sup>(5), (8), (11)</sup>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600 <sup>(10)</sup>	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC\_OUTPJ\_DC}}$ <sup>(5), (6)</sup>	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$f_{\text{DRIFT}}$	Frequency drift after PFDENA is disabled for a duration of 100 $\mu$ s	—	—	$\pm 10$	%
$dK_{\text{BIT}}$	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
$K_{\text{VALUE}}$	Numerator of Fraction	128	8388608	2147483648	—



**Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$f_{RES}$	Resolution of VCO frequency ( $f_{INPFD} = 100$ MHz)	390625	5.96	0.023	Hz

**Notes to Table 31:**

- (1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (2) This specification is limited by the lower of the two: I/O  $f_{MAX}$  or  $f_{OUT}$  of the PLL.
- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4)  $f_{REF}$  is  $f_{IN}/N$  when  $N = 1$ .
- (5) Peak-to-peak jitter with a probability level of  $10^{-12}$  (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition:
  - a. Upstream PLL:  $0.59\text{MHz} \leq \text{Upstream PLL BW} < 1$  MHz
  - b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the  $f_{VCO}$  specification.
- (10) This specification only covers fractional PLL for low bandwidth. The  $f_{VCO}$  for fractional value range 0.05 - 0.95 must be  $\geq 1000$  MHz, while  $f_{VCO}$  for fractional value range 0.20 - 0.80 must be  $\geq 1200$  MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The  $f_{VCO}$  for fractional value range 0.05-0.95 must be  $\geq 1000$  MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The  $f_{VCO}$  for fractional value range 0.20-0.80 must be  $\geq 1200$  MHz.

## DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

**Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)**

Mode	Peformance							Unit
	C1	C2, C2L	I2, I2L	C3	I3, I3L, I3YY	C4	I4	
Modes using one DSP								
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
Modes using two DSPs								
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

**Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)**

Mode	Peformance							Unit
	C1	C2, C2L	I2, I2L	C3	I3, I3L, I3YY	C4	I4	
Modes using Three DSPs								
One complex 18 x 25	425	425	415	340	340	275	265	MHz
Modes using Four DSPs								
One complex 27 x 27	465	465	465	380	380	300	290	MHz

### Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

**Table 33. Memory Block Performance Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 2)**

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
MLAB	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x16 depth <sup>(3)</sup>	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

**Table 33. Memory Block Performance Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
M20K Block	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to <b>Old Data</b> , all supported widths	0	1	525	525	455	400	525	455	400	MHz
	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

**Notes to Table 33:**

- (1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.
- (2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F<sub>MAX</sub>.
- (3) The F<sub>MAX</sub> specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

**Temperature Sensing Diode Specifications**

Table 34 lists the internal TSD specification.

**Table 34. Internal Temperature Sensing Diode Specification**

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

**Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices**

Description	Min	Typ	Max	Unit
I <sub>bias</sub> , diode source current	8	—	200	μA
V <sub>bias</sub> , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	—

## Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface.

General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.



The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

### High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{HCLK\_in}}$ (input clock frequency) True Differential I/O Standards	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	800	5	—	800	5	—	625	5	—	525	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards <sup>(3)</sup>	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	800	5	—	800	5	—	625	5	—	525	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	520	5	—	520	5	—	420	5	—	420	MHz
$f_{\text{HCLK\_OUT}}$ (output clock frequency)	—	5	—	800	5	—	800	5	—	625 <sup>(5)</sup>	5	—	525 <sup>(5)</sup>	MHz

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 3 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{DUTY}$	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
$t_{RISE}$ & $t_{FALL}$	True Differential I/O Standards	—	—	160	—	—	160	—	—	200	—	—	200	ps
	Emulated Differential I/O Standards with three external output resistor networks	—	—	250	—	—	250	—	—	250	—	—	300	ps
TCCS	True Differential I/O Standards	—	—	150	—	—	150	—	—	150	—	—	150	ps
	Emulated Differential I/O Standards	—	—	300	—	—	300	—	—	300	—	—	300	ps
<b>Receiver</b>														
True Differential I/O Standards - $f_{HSDRDP}$ (data rate)	SERDES factor J = 3 to 10 <sup>(11), (12), (13), (14), (15), (16)</sup>	150	—	1434	150	—	1434	150	—	1250	150	—	1050	Mbps
	SERDES factor J $\geq 4$	150	—	1600	150	—	1600	150	—	1600	150	—	1250	Mbps
	LVDS RX with DPA <sup>(12), (14), (15), (16)</sup>	150	—	1600	150	—	1600	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	Mbps
	SERDES factor J = 1, uses SDR Register	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	Mbps

## Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

**Table 44. Worst-Case DCD on Stratix V I/O Pins <sup>(1)</sup>**

Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4, I4		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

**Note to Table 44:**

(1) The DCD numbers do not cover the core clock network.

## Configuration Specification

### POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

**Table 45. Fast and Standard POR Delay Specification <sup>(1)</sup>**

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

**Note to Table 45:**

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

### JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

**Table 46. JTAG Timing Parameters and Values for Stratix V Devices**

Symbol	Description	Min	Max	Unit
t <sub>JCP</sub>	TCK clock period <sup>(2)</sup>	30	—	ns
t <sub>JCP</sub>	TCK clock period <sup>(2)</sup>	167	—	ns
t <sub>JCH</sub>	TCK clock high time <sup>(2)</sup>	14	—	ns
t <sub>JCL</sub>	TCK clock low time <sup>(2)</sup>	14	—	ns
t <sub>JPSU (TDI)</sub>	TDI JTAG port setup time	2	—	ns
t <sub>JPSU (TMS)</sub>	TMS JTAG port setup time	3	—	ns

**Table 46. JTAG Timing Parameters and Values for Stratix V Devices**

Symbol	Description	Min	Max	Unit
$t_{JPH}$	JTAG port hold time	5	—	ns
$t_{JPCO}$	JTAG port clock to output	—	11 <sup>(1)</sup>	ns
$t_{JPZX}$	JTAG port high impedance to valid output	—	14 <sup>(1)</sup>	ns
$t_{JPXZ}$	JTAG port valid output to high impedance	—	14 <sup>(1)</sup>	ns

**Notes to Table 46:**

- (1) A 1 ns adder is required for each  $V_{CCIO}$  voltage step down from 3.0 V. For example,  $t_{JPCO}$  = 12 ns if  $V_{CCIO}$  of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.
- (2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

## Raw Binary File Size

For the POR delay specification, refer to the “POR Delay Specification” section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices”.

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

**Table 47. Uncompressed .rbf Sizes for Stratix V Devices**

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) <sup>(4), (5)</sup>
Stratix V GX	5SGXA3	H35, F40, F35 <sup>(2)</sup>	213,798,880	562,392
		H29, F35 <sup>(3)</sup>	137,598,880	564,504
	5SGXA4	—	213,798,880	563,672
	5SGXA5	—	269,979,008	562,392
	5SGXA7	—	269,979,008	562,392
	5SGXA9	—	342,742,976	700,888
	5SGXAB	—	342,742,976	700,888
	5SGXB5	—	270,528,640	584,344
	5SGXB6	—	270,528,640	584,344
	5SGXB9	—	342,742,976	700,888
	5SGXBB	—	342,742,976	700,888
Stratix V GT	5SGTC5	—	269,979,008	562,392
	5SGTC7	—	269,979,008	562,392
Stratix V GS	5SGSD3	—	137,598,880	564,504
	5SGSD4	F1517	213,798,880	563,672
		—	137,598,880	564,504
	5SGSD5	—	213,798,880	563,672
	5SGSD6	—	293,441,888	565,528
	5SGSD8	—	293,441,888	565,528

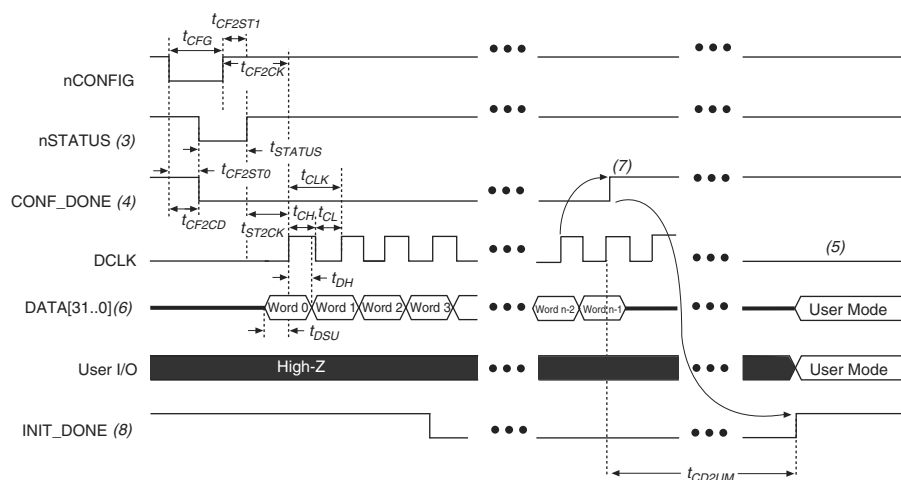




## FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is 1.

**Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 <sup>(1), (2)</sup>**



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP x16, use DATA [15..0]. For FPP x8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

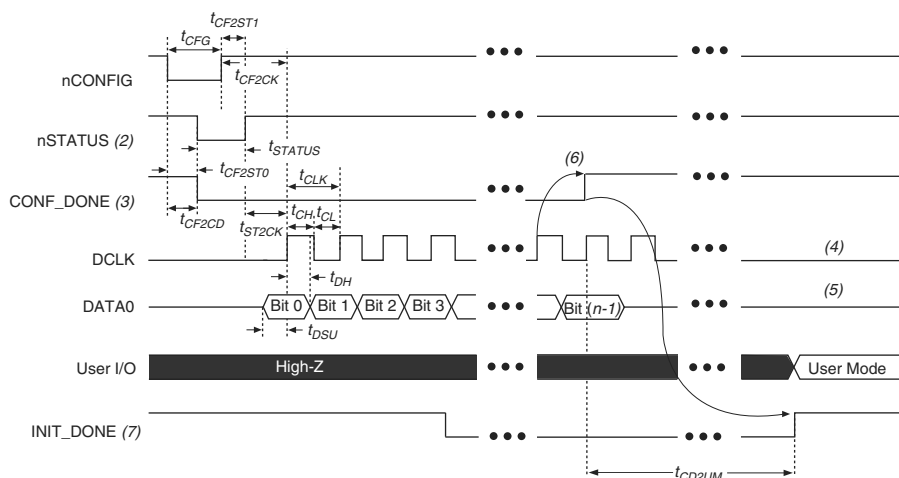
Symbol	Parameter	Minimum	Maximum	Units
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μs
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

**Notes to Table 53:**

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2)  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

**Figure 15. PS Configuration Timing Waveform <sup>(1)</sup>****Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Table 60. Glossary (Part 4 of 4)**

Letter	Subject	Definitions
<b>V</b>	$V_{CM(DC)}$	DC common mode input voltage.
	$V_{ICM}$	Input common mode voltage—The common mode of the differential signal at the receiver.
	$V_{ID}$	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
	$V_{IH}$	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage
	$V_{IH(DC)}$	High-level DC input voltage
	$V_{IL}$	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage
	$V_{IL(DC)}$	Low-level DC input voltage
	$V_{OCM}$	Output common mode voltage—The common mode of the differential signal at the transmitter.
	$V_{OD}$	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	$V_{SWING}$	Differential input voltage
	$V_X$	Input differential cross point voltage
	$V_{OX}$	Output differential cross point voltage
<b>W</b>	W	High-speed I/O block—clock boost factor
<b>X</b>	—	—
<b>Y</b>		
<b>Z</b>		

**Table 61. Document Revision History (Part 2 of 3)**

Date	Version	Changes
November 2014	3.3	<ul style="list-style-type: none"> <li>■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.</li> <li>■ Added the I3YY speed grade to the <math>V_{CC}</math> description in Table 6.</li> <li>■ Added the I3YY speed grade to <math>V_{CCHIP\_L}</math>, <math>V_{CCHIP\_R}</math>, <math>V_{CCHSSI\_L}</math>, and <math>V_{CCHSSI\_R}</math> descriptions in Table 7.</li> <li>■ Added 240-<math>\Omega</math> to Table 11.</li> <li>■ Changed CDR PPM tolerance in Table 23.</li> <li>■ Added additional max data rate for fPLL in Table 23.</li> <li>■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.</li> <li>■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.</li> <li>■ Changed CDR PPM tolerance in Table 28.</li> <li>■ Added additional max data rate for fPLL in Table 28.</li> <li>■ Changed the mode descriptions for MLAB and M20K in Table 33.</li> <li>■ Changed the Max value of <math>f_{HCLK\_OUT}</math> for the C2, C2L, I2, I2L speed grades in Table 36.</li> <li>■ Changed the frequency ranges for C1 and C2 in Table 39.</li> <li>■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.</li> <li>■ Added note about nSTATUS to Table 50, Table 51, Table 54.</li> <li>■ Changed the available settings in Table 58.</li> <li>■ Changed the note in “Periphery Performance”.</li> <li>■ Updated the “I/O Standard Specifications” section.</li> <li>■ Updated the “Raw Binary File Size” section.</li> <li>■ Updated the receiver voltage input range in Table 22.</li> <li>■ Updated the max frequency for the LVDS clock network in Table 36.</li> <li>■ Updated the DCLK note to Figure 11.</li> <li>■ Updated Table 23 <math>VO_{CM}</math> (DC Coupled) condition.</li> <li>■ Updated Table 6 and Table 7.</li> <li>■ Added the DCLK specification to Table 55.</li> <li>■ Updated the notes for Table 47.</li> <li>■ Updated the list of parameters for Table 56.</li> </ul>
November 2013	3.2	■ Updated Table 28
November 2013	3.1	■ Updated Table 33
November 2013	3.0	■ Updated Table 23 and Table 28
October 2013	2.9	■ Updated the “Transceiver Characterization” section
October 2013	2.8	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59</li> <li>■ Added Figure 1 and Figure 3</li> <li>■ Added the “Transceiver Characterization” section</li> <li>■ Removed all “Preliminary” designations.</li> </ul>

